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# The XH cryogenic detector system: overview and recent studies

A HPGe micro-strip sensor

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High Precision X-ray Measurements 2025

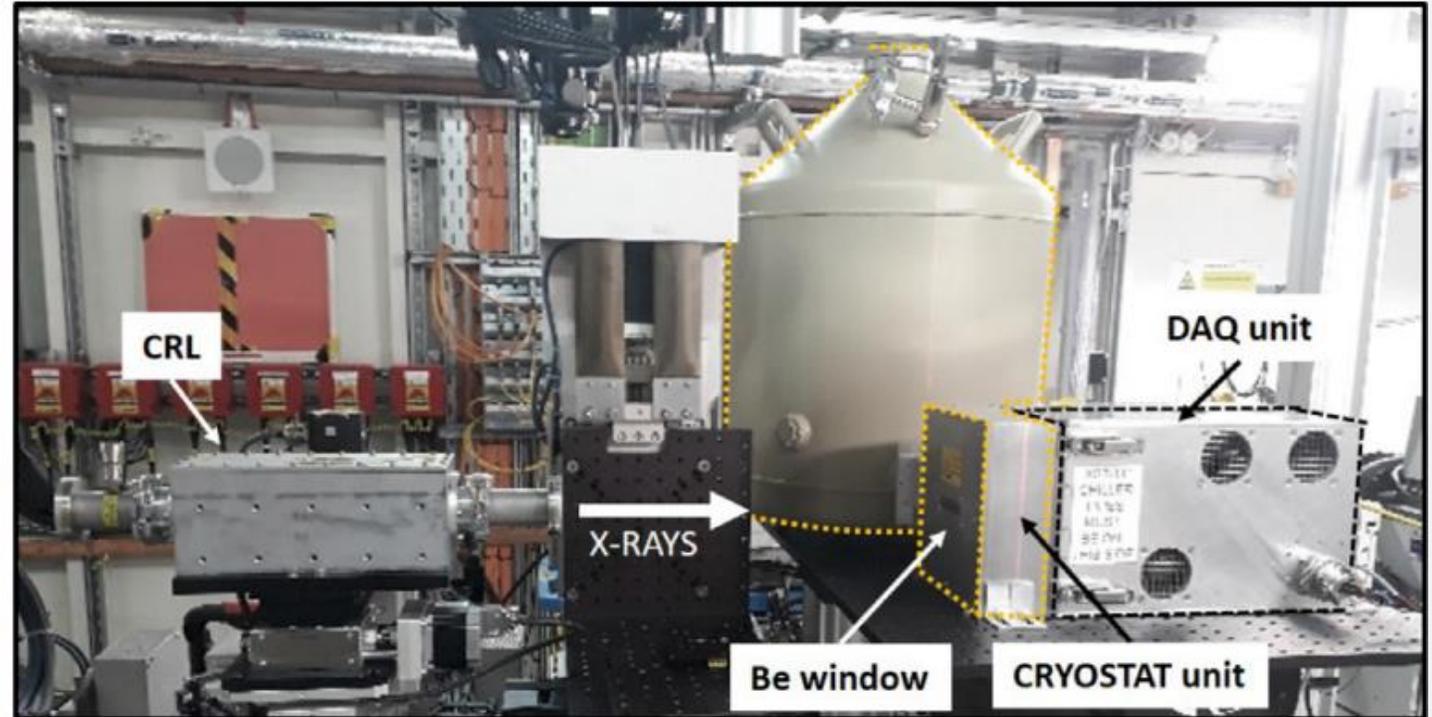


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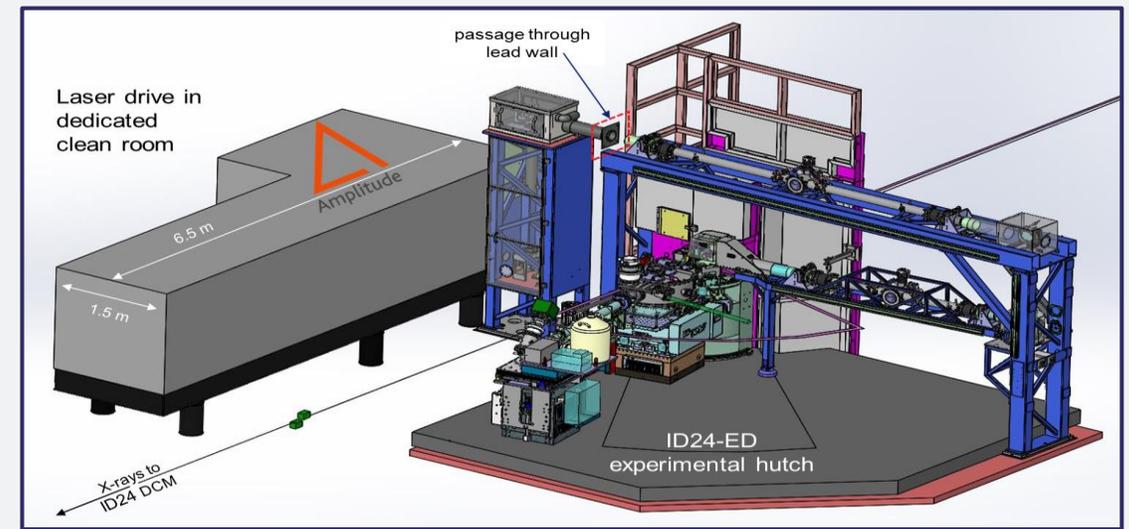
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- Summary

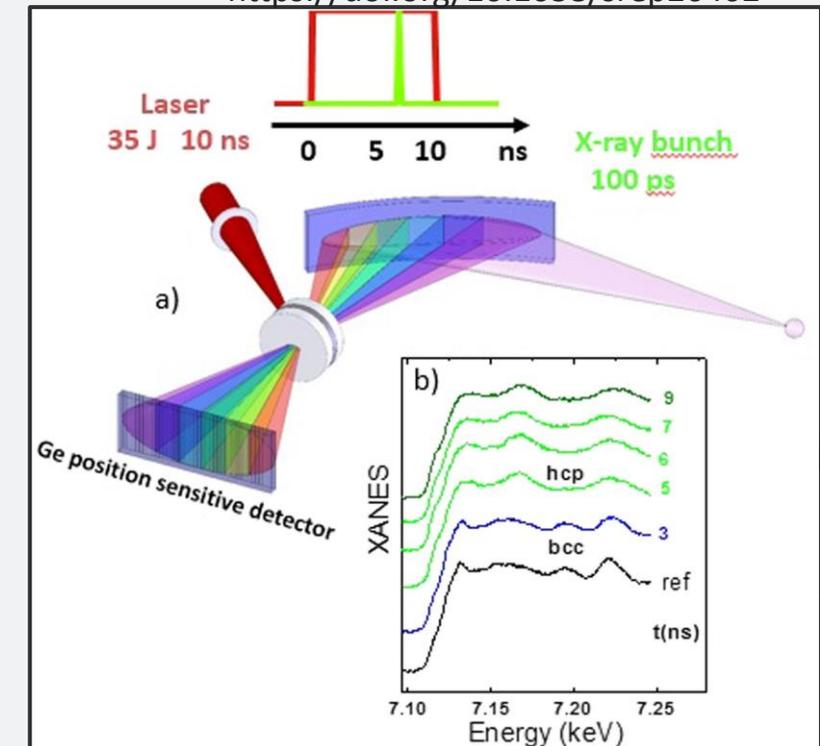


# Experimental application

- XH is a detector currently deployed at the High Power Laser Facility (HPFL) at ESRF-EBS ID24.
- It is used in time-resolved Energy Dispersive X-ray Absorption Fine Structure (EXAFS).
- EBS beams are combined with the high-power laser to perform dynamic compression experiments in the ns time-scale.
- The extreme conditions of pressure and temperature created in the sample are used to study structure and properties of matter for solid state physics, materials and energy.
- A representative case is the study of warm dense matter, relevant to the description of planetary interiors.



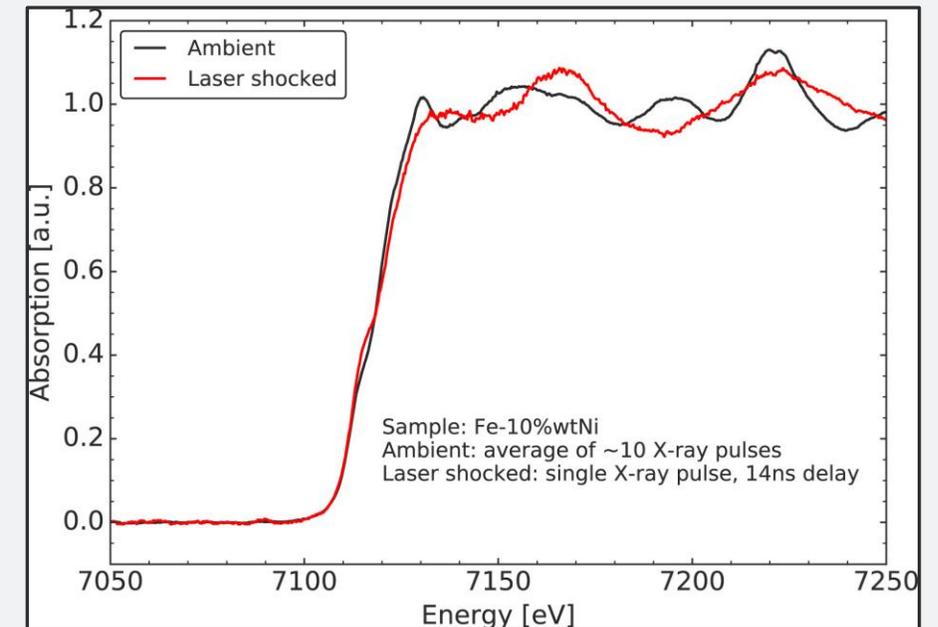
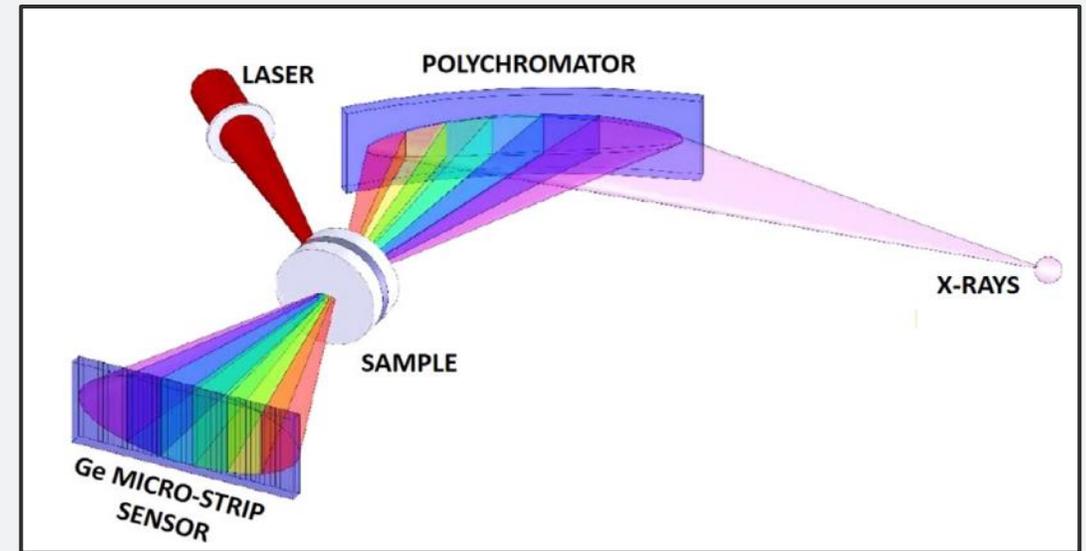
<https://doi.org/10.1038/srep26402>



Probing local and electronic structure in Warm Dense Matter: single pulse synchrotron x-ray absorption spectroscopy on shocked Fe

# Experimental application

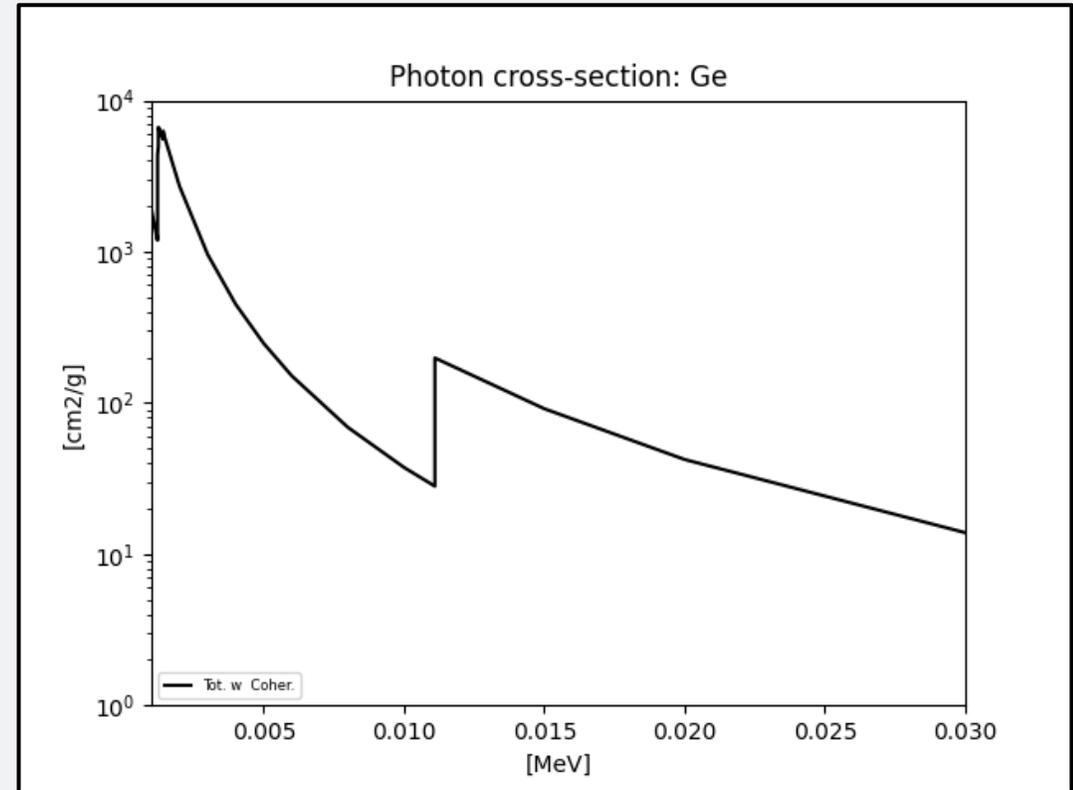
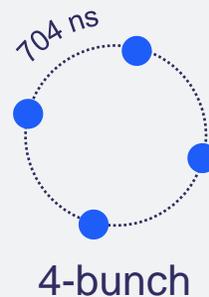
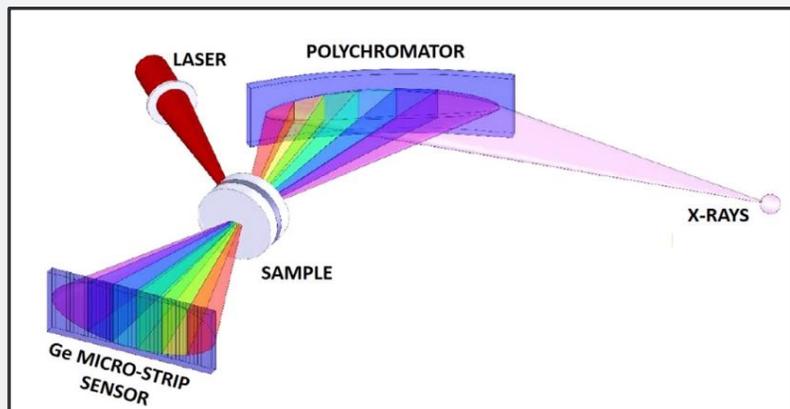
- XH deploys an HPGe micro-strip sensor to detect the polychromatic transmitted pink beam.
- A back-illuminated HPGe sensor, with 1024 strips and 50  $\mu\text{m}$  pitch.
- Each strip position corresponds to a different spectral component of the dispersed beam.
- EBS provides bright X-ray pulses, reducing photon statical noise on single shot measurements – sample is destroyed during exposure.



<https://doi.org/10.1016/j.nima.2020.164932>

# Experimental application

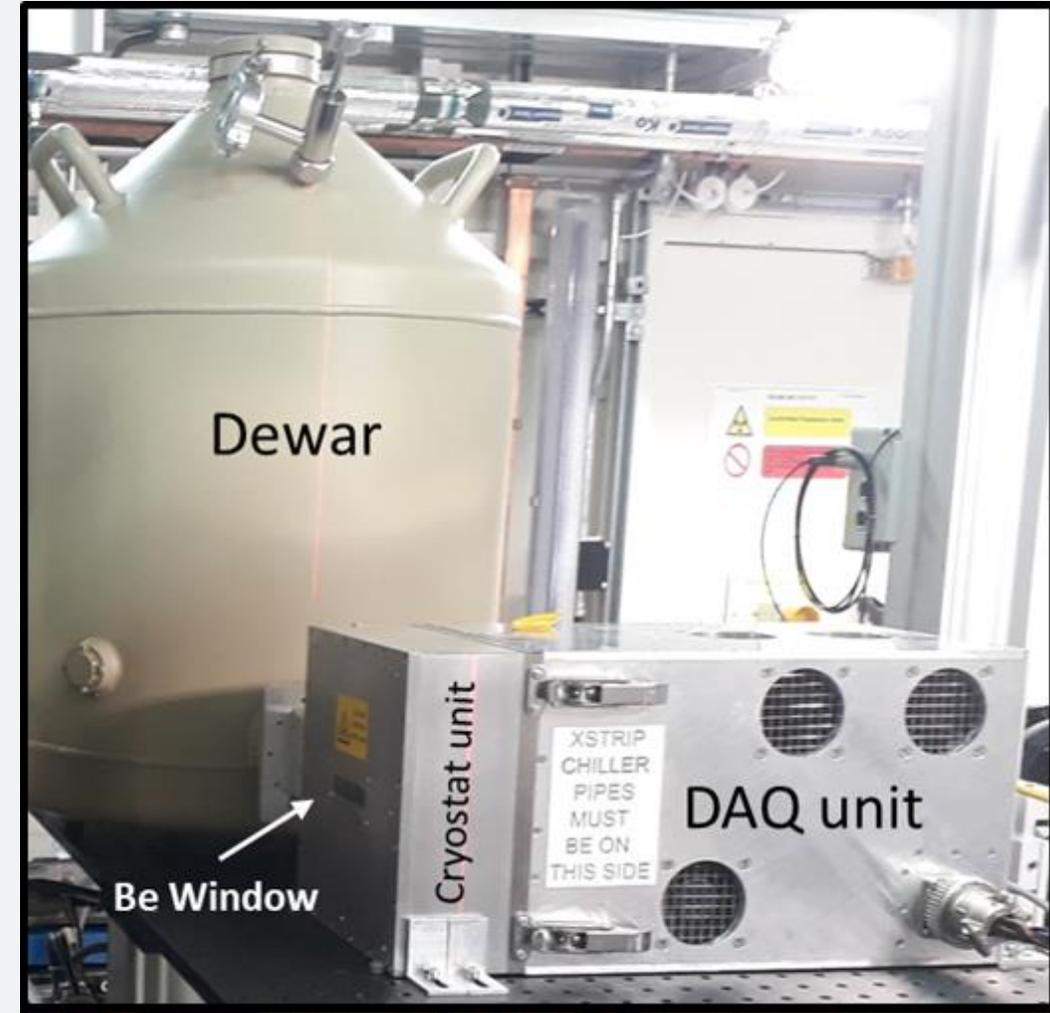
- At ID24, the primary energy range is: 5-27 keV
- The highest flux is expected at 7 keV with 4-bunch fill pattern:  $39.6 * 10^6 \gamma / \text{bunch}$  (i.e. every 700ns, leading to  $5.6 * 10^{13} \gamma / \text{s}$  total).
- Photons hit the detector over an area 50mm x 0.1mm.
- w/o sample:  $\sim 1 * 10^{13} \gamma \text{ mm}^{-2} \text{ s}^{-1}$  are transmitted to the HPGe sensor.
- This creates a harsh radiation environment for the sensor.



# XH: cryogenic detector system

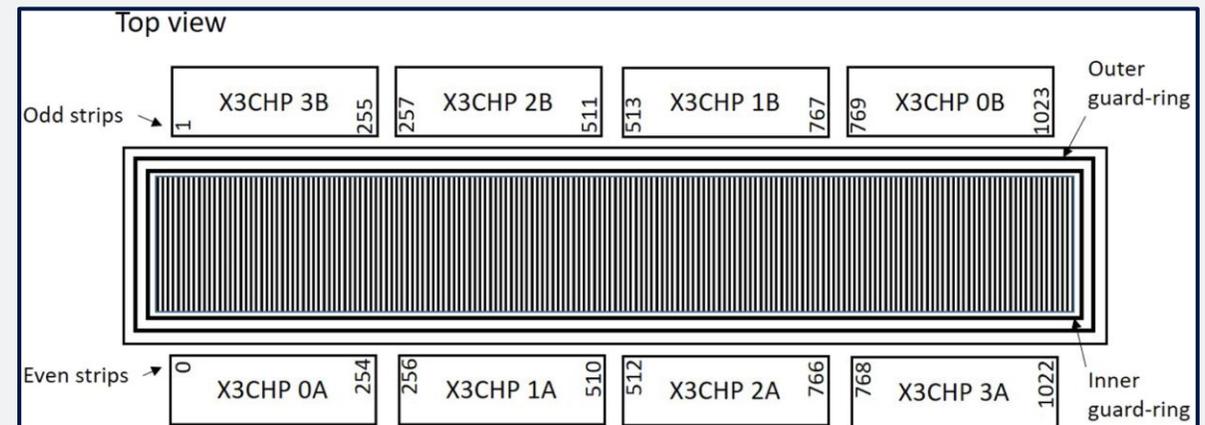
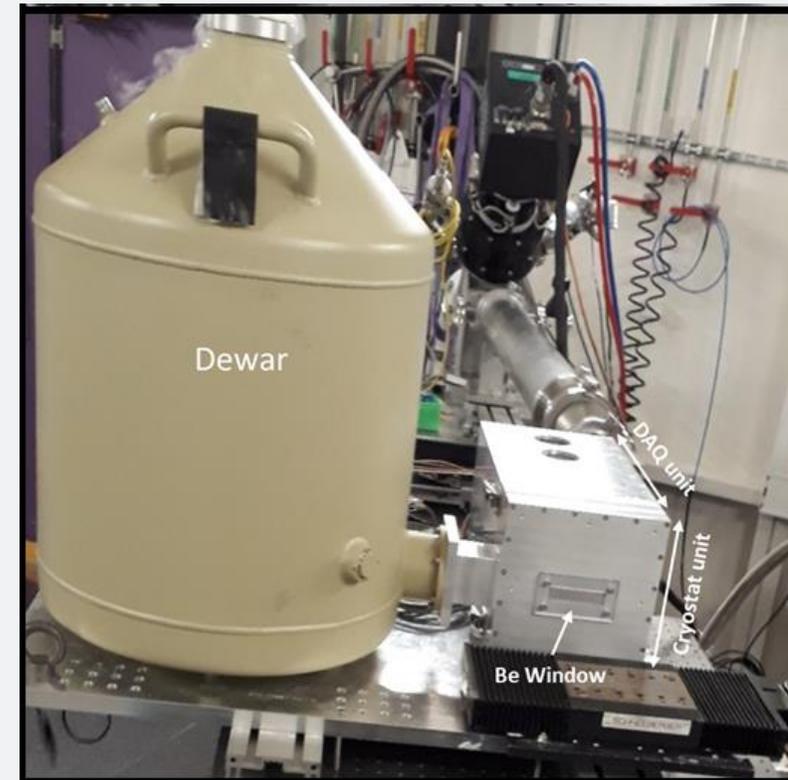
The system is made of two main units:

- the cryostat unit
- the data acquisition unit



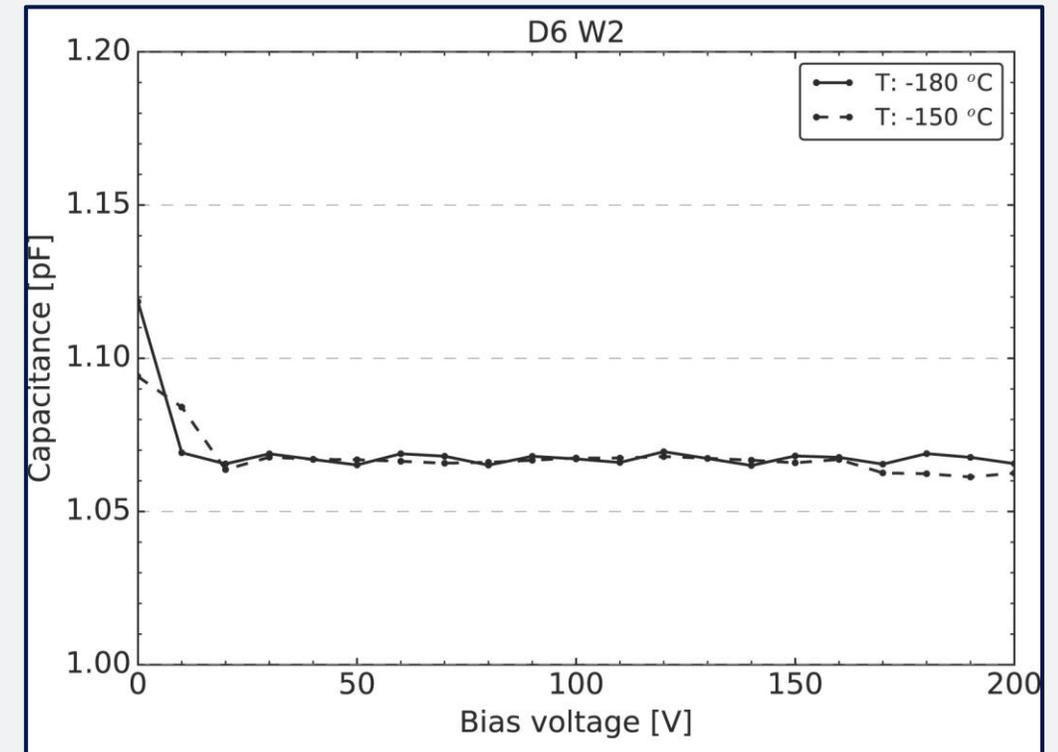
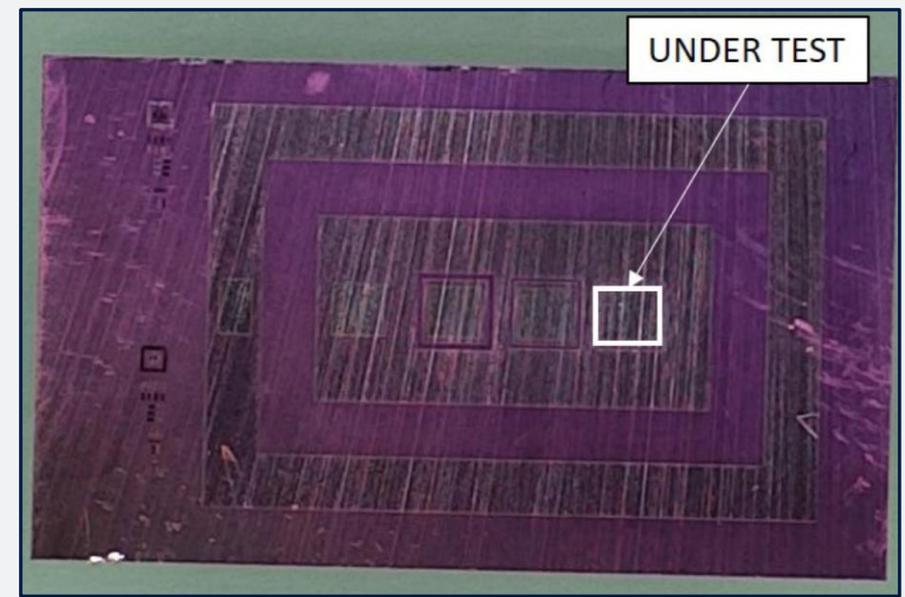
# Cryostat unit

- Liquid Nitrogen (LN2) Dewar:
  - 30L, commercial off the shelf
- Detector chassis and internal cooling mechanics:
  - Custom made
  - Be window for X-rays access
- HPGe micro-strip sensor:
  - Procured from commercial supplier:
    - Mirion Technologies
  - 1024 strips, 50  $\mu\text{m}$  pitch, 1.5 mm thickness
- Front-End electronics:
  - Custom made by STFC
  - X3CHIP, charge integrating
  - 128 channels/ASIC
  - Outer and Inner guard ring



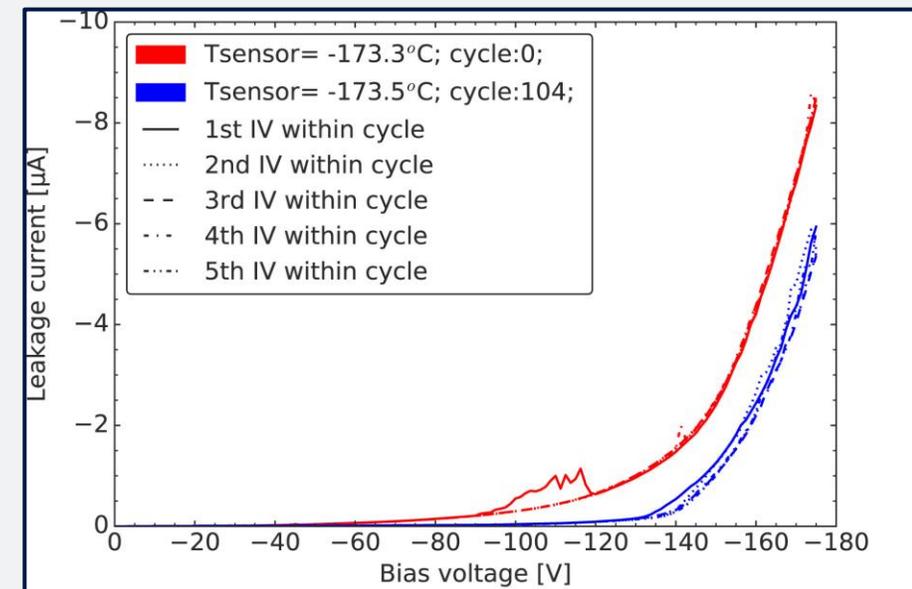
# HPGe test pads

- Test structures with a similar set-up to the strip sensor were also manufactured.
- Capacitance – Voltage characteristics were assessed.
- Sensor fully depletes at  $\sim 30\text{V}$  at 2 representative temperatures.

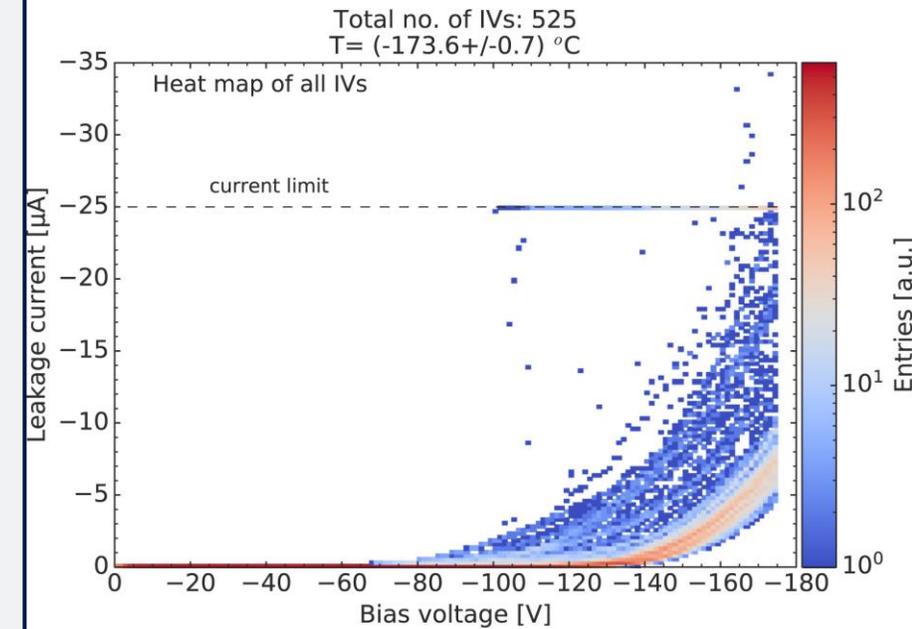


# Stress tests on the cryostat unit

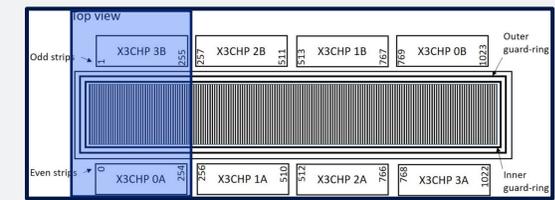
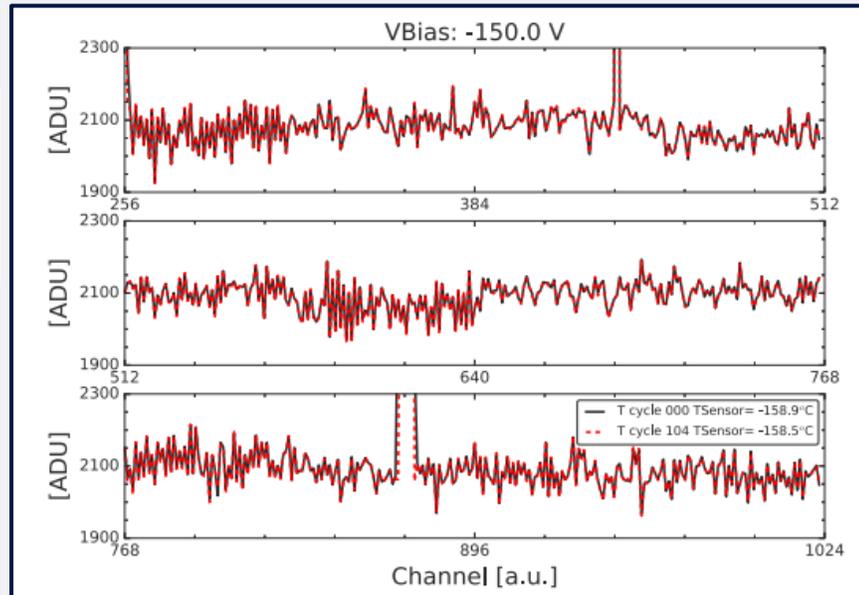
- The cryostat unit was thermally cycled 105 times.
  - Average  $\Delta T \sim 150 \text{ }^\circ\text{C}$ , Max  $\Delta T 173^\circ\text{C}$
- Sensor, electronics, interconnection were monitored at each iteration.
- In total, 525 IV curves were taken within 105 temperature cycles (i.e. 5 IVs/Tcycle).
- The system was 'baked-out' 25 times over the period.
  - Bakeout consisted of vacuum pumping the cryostat at  $\sim +55^\circ\text{C}$  for 4 days.
- No evidence of failure detected at component of system level.
  - IVs always restored at baseline value after bakeout
  - No wire bonds detached
  - No front-end chip deteriorated



(a)



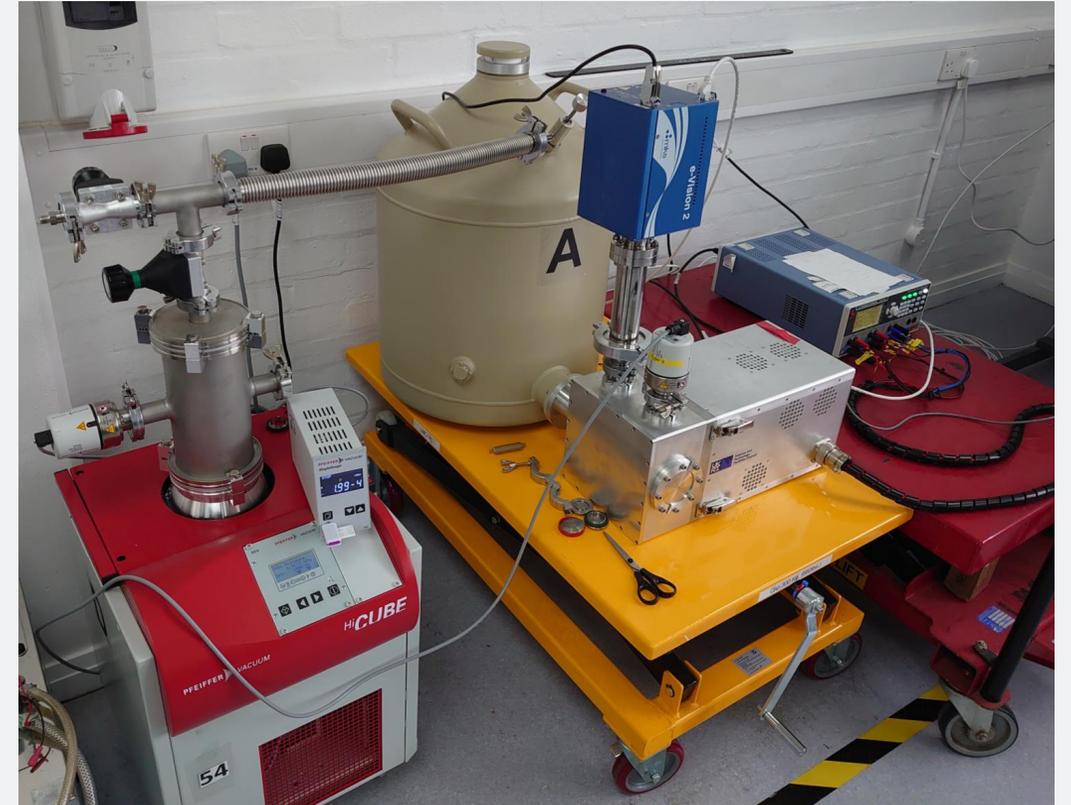
(b)



Not considered in the study, mechanically damaged.

# Vacuum studies on cryostat unit

- The cryostat unit houses the HPGe sensor and the front-end electronics.
- We are performing a set of measurements to characterise the vacuum deterioration inside the cryostat during long term operation.
- Investigating the interplay between the internal outgassing effects and the surface current on the sensor.
- A cryostat unit was equipped to measure vacuum.

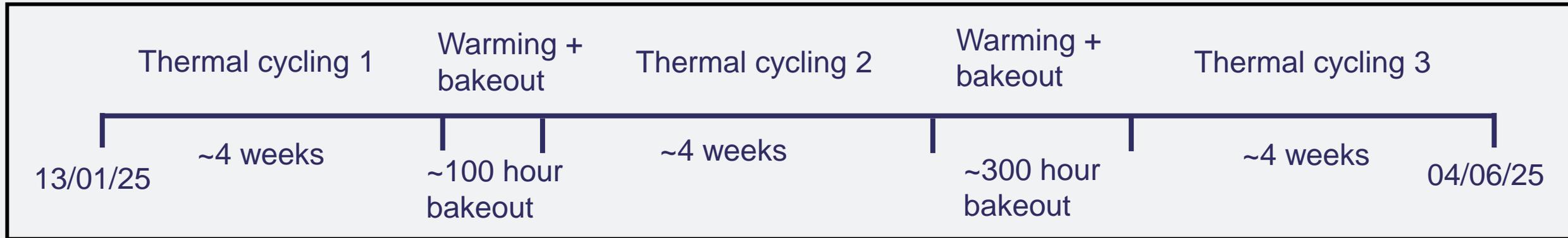


# Experimental set-up:

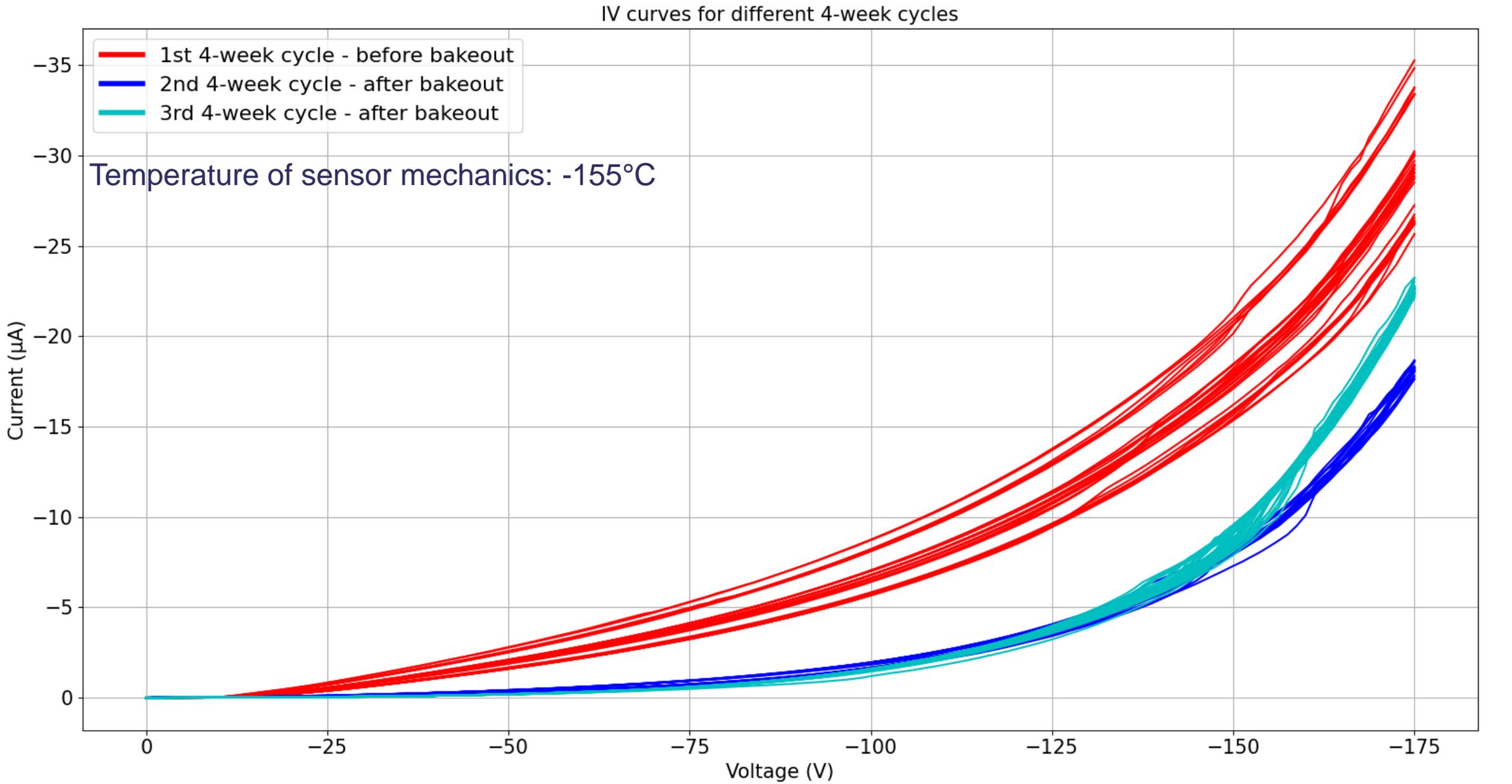


# Procedure and timeline

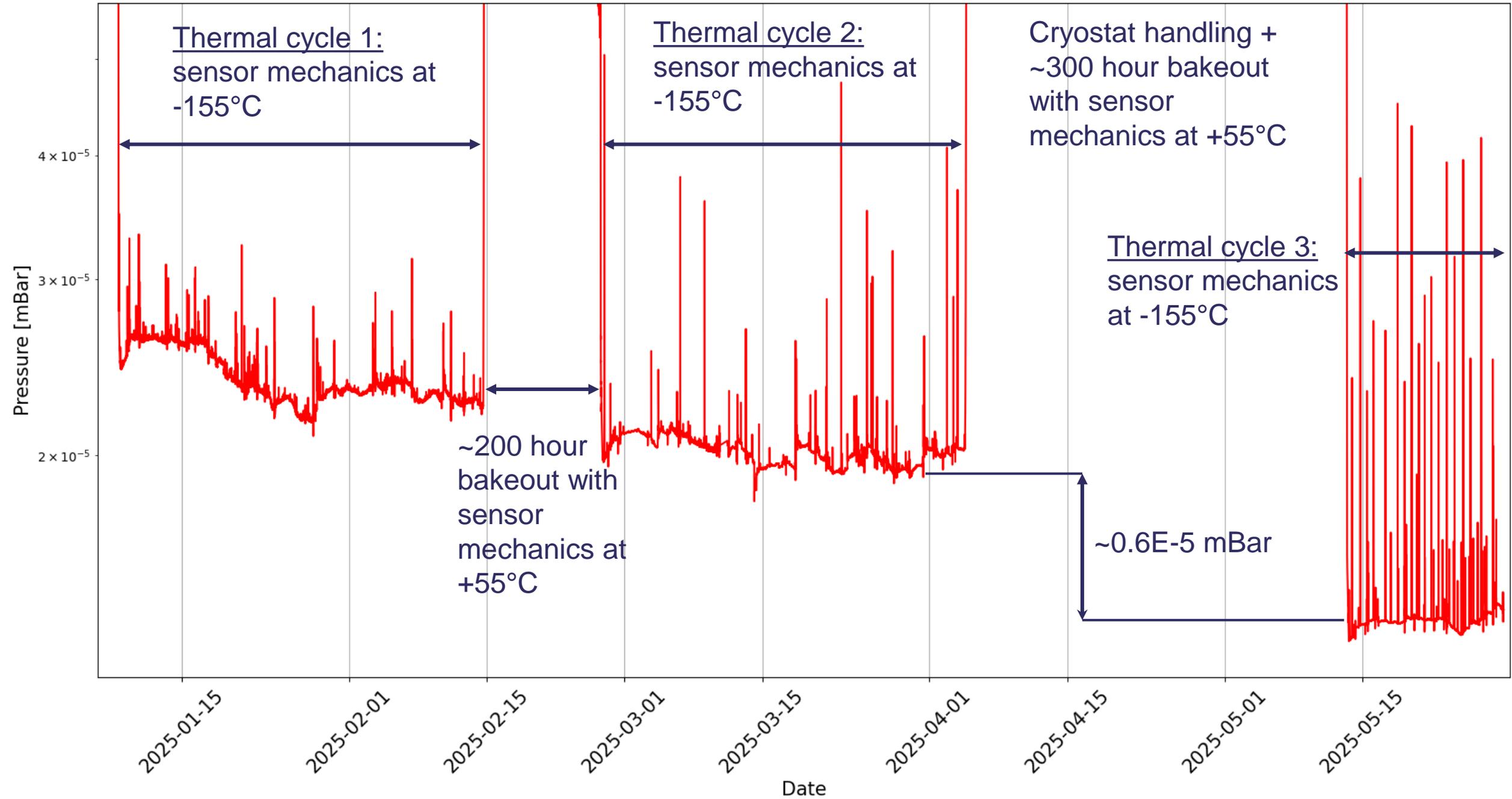
- Applied high operational current to the headboard and heated it with a PID controller to  $-50^{\circ}\text{C}$ .
- Continually took IVs, residual gas spectra and vacuum data within the 'Thermal cycle'.
- After 4 weeks of this, perform bakeout and repeat.



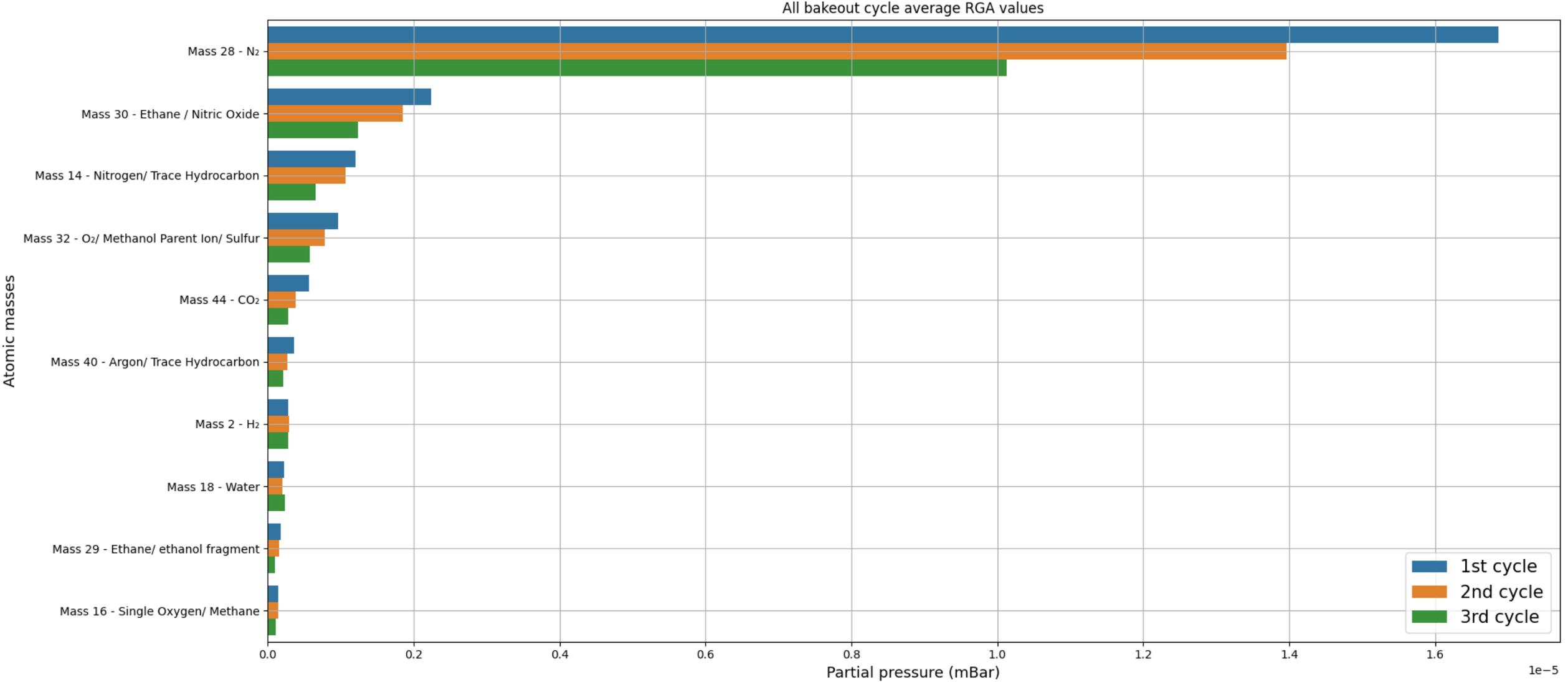
# Pre and post-bakeout IV curves – at operational sensor temperature



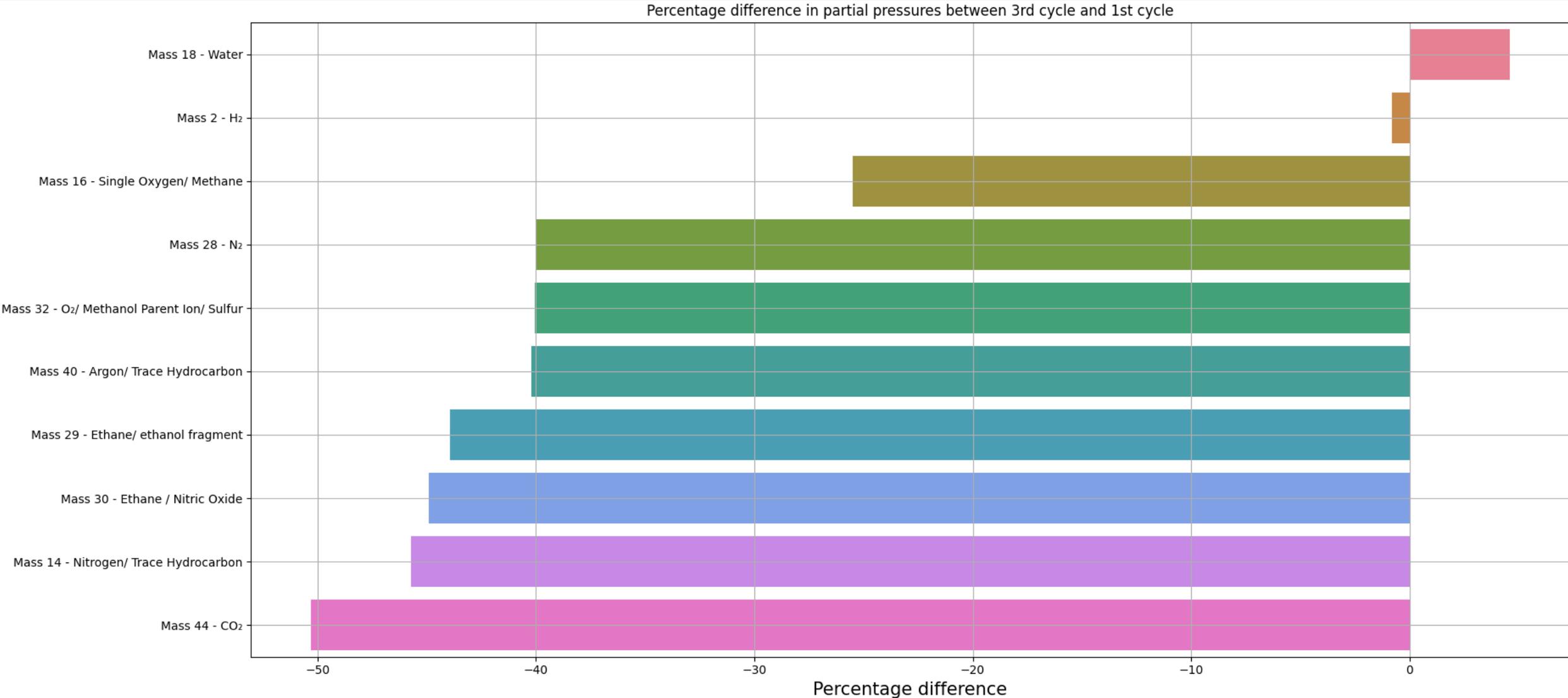
Pressure against date for XH



# Residual Gas Spectra – Thermal cycle 1 and 3 averaged RGA values



# Residual Gas Spectra – Percentage difference between thermal cycle 1 and 3 averaged RGA values



# Future studies - irradiations

- The XH cryostat has been fitted with a beryllium window.
- Daresbury Laboratory has an X-ray irradiation chamber which will be used to assess how the vacuum, residual gases and leakage current of the XH system perform under constant irradiation.
- Irradiating at 20 keV and 20 mA for prolonged periods
- Higher flux may be required at the ESRF.



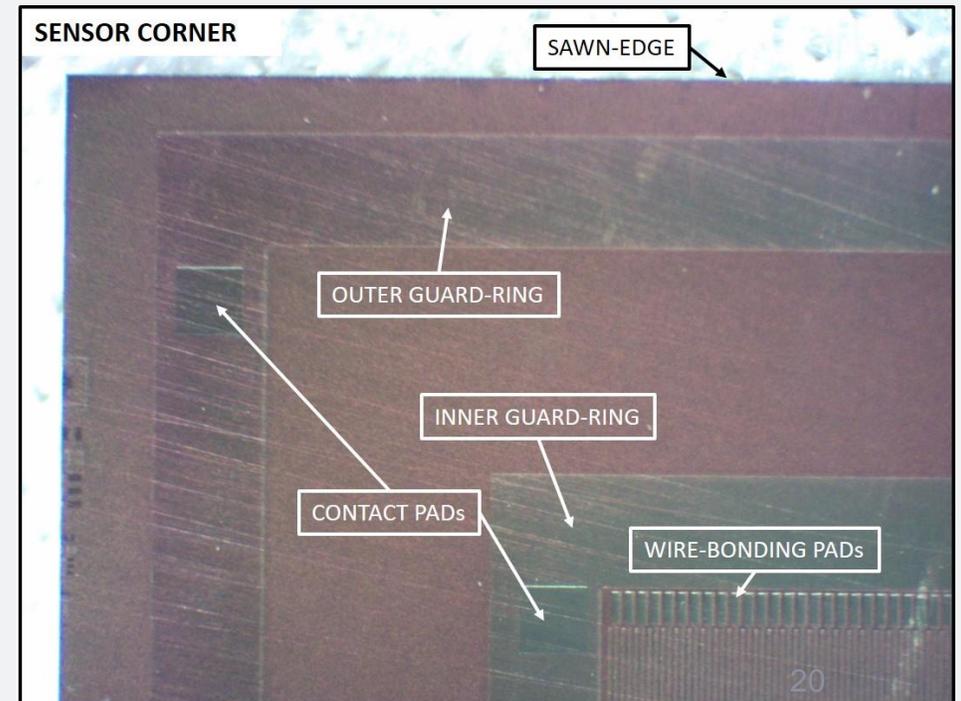
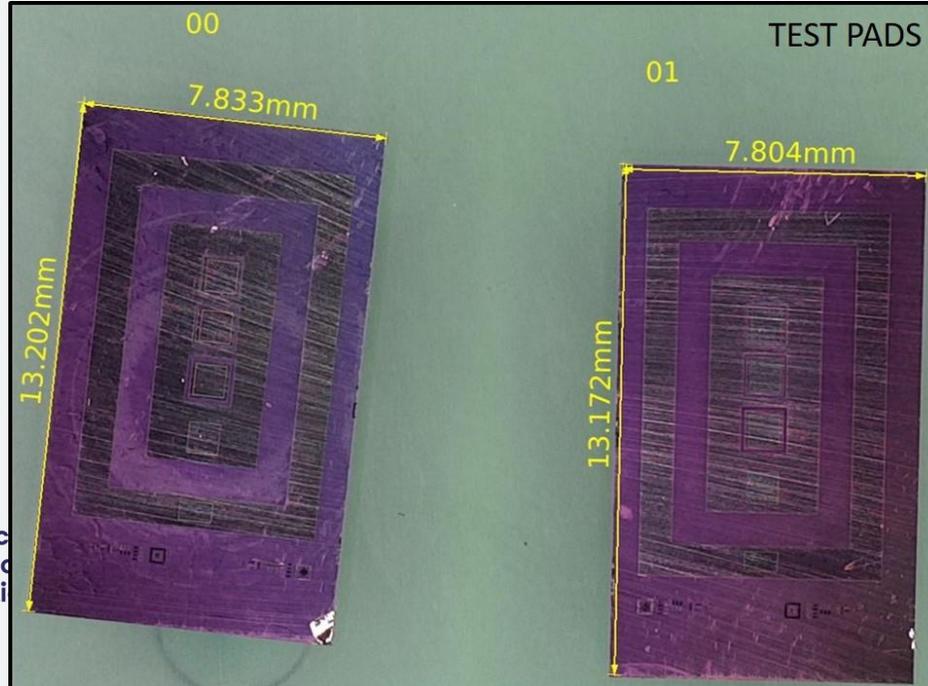
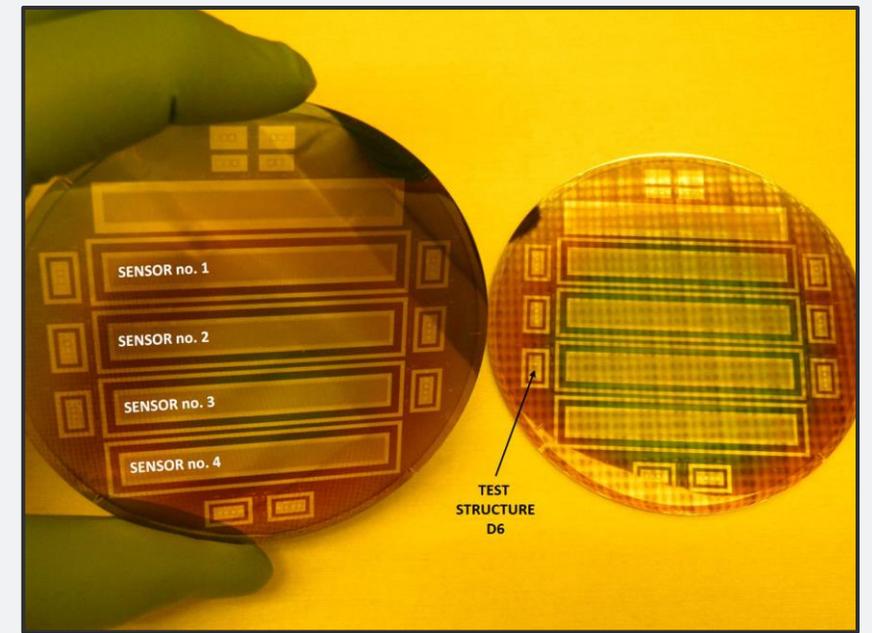
# Summary

- XH is a HPGe microstrip sensor used for Energy Dispersive X-ray spectroscopy.
- Installed at the ESRF HPLF beamline analysing extreme states of matter
  - operated in a radiation harsh environment.
- The XH system was thermally cycled many times and remained consistent.
- Bakeouts have a direct impact on detector leakage current and cryostat vacuum level.
- Future research will assess radiation induced contamination of the sensor surface.

# Back-up

# HPGe micro-strip sensor

- 90 mm diameter wafers manufactured by Mirion Technologies
- Size: 1024 strips
- Strip pitch: 50  $\mu\text{m}$  with 20 $\mu\text{m}$  gap
- Strip length: 5mm
- Sensor thickness: 1.5mm
- Two guard-rings
- Interleaved wire-bonding pads
- Back illuminated



# QC on cryostat unit: production version

- We perform a series of quality control measurements on cryostat units to validate the performance of the unit.
- IV characteristics:
  - 10 IVs back-to-back up 200V
  - 24hrs apart i.e. before after burn-in test
- Leakage current burn-in test:
  - 24 hrs at 200V
- Temperature Vs Pwr:
  - Sensor temperature  $< -170$  C @  $\sim 12$ W front end power (i.e head-boards)
- Visible light response:
  - Basic response test via an LED installed inside the cryostat

